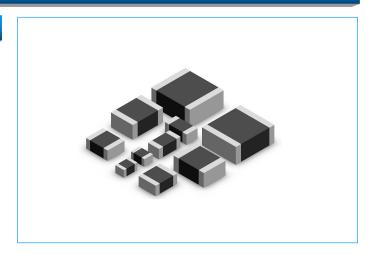




## SV1812N5R5G0B

### **Features**

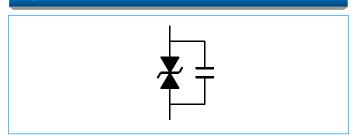
- RoHS Compliant.
- ♦ Meet IEC 61000-4-5 standard.
- SMD type zinc oxide based ceramic chip.
- Insulator overcoat keeps excellent low and stable leakage current.
- Quick response time (<0.5ns).</li>
- High transient current capability.
- High reliability.
- ◆ Compact size for EIA 1812.



### **Applications**

Protection against high working voltage applications
 Related transient over voltage.

### **Equivalent Circuits**



### **Electrical Characteristics (25±5℃)**

Symbol	Minimum	Typical	Maximum	Units	
V <sub>RMS</sub>	_	_	4	V	
V <sub>DC</sub>	_	_	5.5	V	
Vv	9	_	14	V	
Vc	_	_	30	V	
СР	_	5400	_	pF	
I <sub>max</sub>	_	_	800	А	

#### Notes:

V<sub>RMS</sub> - Maximum AC operating voltage the varistor can maintain and not exceed 10µA leakage current.

 $V_{DC}$  - Maximum DC operating voltage the varistor can maintain and not exceed 10 $\mu$ A leakage current.

 $\ensuremath{V_{V}}\xspace$  - Voltage across the device measure at 1mA DC current.

Equivalent to VB "breakdown voltage".

 $\ensuremath{V_\text{C}}$  - Maximum peak current across the varistor with 8/20µs waveform and 5A pulse current.

Cp - Device capacitance measured with zero volt bias 1Vrms at 1KHZ .

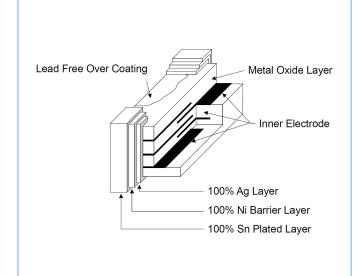
 $I_{\text{max}}$  - Maximum peak current which may be applied with 8/20 $\mu\text{s}$  waveform without device failure.

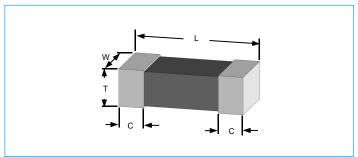




# SV1812N5R5G0B

### **Construction & Dimensions**





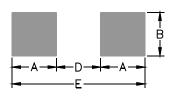
Size EIA (EIAJ)	1812 (4532)
Symbol	Millimeters
L	4.50±0.40
w	3.20±0.30
Т	2.5 Max
С	0.60±0.30

## Pad Layouts & Precaution for handling of substrate

#### Solder cream in reflow soldering

Refer to the recommendable land pattern as printing mask pattern for solder cream.

(1) Print solder in a thickness of 150 to 200 $\mu m$ 



Size EIA (EIAJ)	1812 (4532)	
Symbol	Millimeters	
Α	1.5	
В	3.6	
D	3.0	
E	6.0	

### Precaution for handling of substrate

Do not exceed to bend the board after soldering thes product extremely. (reference examples)

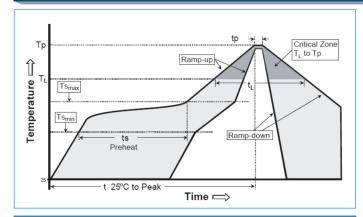
- Mounting place must be as far as possible from the position, which is close to the break line of board or on the line of large holes of board.
- Do not bend extremely the board, in mounting another component. If necessary, use back-up pin (support pin) to prevent from bending extremely.
- Do not break the board by hand. We recommend to use the machine or the jig to break it.





# SV1812N5R5G0B

## **Soldering Parameters**



### **Precaution for Soldering**

Note that this product will be easily damaged by rapid heating, rapid cooling or local heating.

Do not give heat shock over 100°C in the process of soldering. We recommend to take preheating and gradual cooling

### Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

- 1) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30W
- 2) The soldering gun tip shall not touch this product directly.

#### Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.

Reflow Co	ndition	Pb-Free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	+150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	+200°C	
	-Time (min to max) (t <sub>s</sub> )	60 -180 Seconds	
T <sub>S(max)</sub> to T	<sub>P</sub> - Ramp-up Rate	3°C/Second Max	
Deflam	- Temperature (T <sub>L</sub> ) (Liquidus)	+217°C	
Reflow	- Time (min to max) (t <sub>L</sub> )	60 -150 Seconds	
Peak Temp	perature (T <sub>P</sub> )	260 °C	
Time withi	n 5°C of actual peak ıre (t <sub>P</sub> )	20-40 Seconds	
Ramp-dow	vn Rate	6°C/Second Max	
Time 25°C	to peak Temperature (T <sub>P</sub> )	8 minutes Max	

### **General Technical Data**

Operating Temperat	ture	-40 ~ +125°C	
Storage Temperatur	re	-40 ~ +125°C	
Response Time		<1 ns	
Solderability		245±5°C,5 +0/-0.5sec	
Solder leach resistance		260±5°C, 10±1sec	
	Storage Temperature	5 ~ 40°C	
Taping Package Storage Condition	Relative Humidity	To 65%	
	Storage Time	12 Months max	

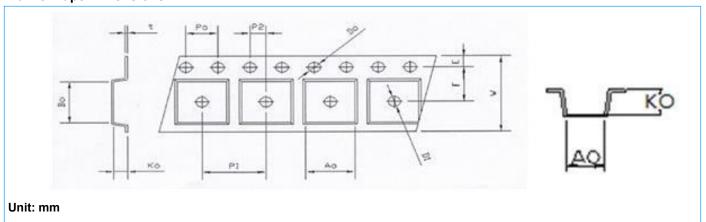




# SV1812N5R5G0B

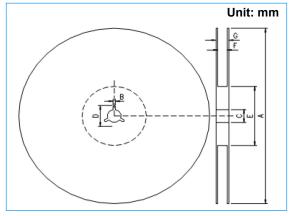
## **Packaging Information**

### **Carrier Tape Dimensions**



Symbol	W	Е	F	D0	D1	P0	P1	P2	10Po
1812	12.0±0.15	1.75±0.10	5.5±0.10	1.55±0.10	1.55±0.10	4.0±0.10	8.0±0.10	2.0±0.10	40.0±0.20
Symbol	Во	Ao	Ко	t					
1812	4.9±0.10	3.5±0.10	2.2±0.10	0.25±0.5	-	-	-		

## **Taping Reel Dimensions**



Symbol	A	В	С	D	Е	F	G
1812	178.0±1.0	2.5±0.5	13.0±0.5	25.0±1.0	60.2±0.5	13.0± 0.5	16.0±0.5

### **Taping Specifications**

There Shall be the portion having no product in both the head and the end of taping, and there shall be the cover tape in the heat of taping.

## Quantity of products in the taping package

SIZE EIA (EIAJ)	1812 (4532)		
Standard Packing Quantity (PCS / reel)	1,000		